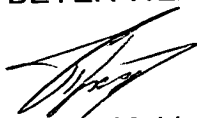


## REMARKS

Applicant believes that all pending claims are allowable and respectfully requests a Notice of Allowance for this application from the Examiner. Should the Examiner believe that a telephone conference would expedite the prosecution of this application, the undersigned can be reached at the telephone number set out below.

Respectfully submitted,  
BEYER WEAVER & THOMAS, LLP



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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

1. (Twice Amended) A plasma processing system, said plasma processing system comprising:

a substantially cylindrical plasma processing chamber used to process a substrate said substantially cylindrical plasma processing chamber including a top region and a peripheral region;

a gas flow system coupled to said plasma processing chamber, said gas flow system controlling flow of input gas into at least two different regions of said plasma processing chamber; said input gas being a source gas suitable for use to etch the substrate in the plasma processing chamber; [and]

wherein the at least two different regions include at least one peripheral region of the plasma processing chamber; and

wherein said peripheral region of said plasma processing chamber does not include any points of said top region of said plasma processing chamber.